

CLAIMS

What is claimed is:

1. A heat-dissipating plate module comprising:

5 a heat-conductive base, which is installed on a heat-generating component of
an electronic device; and

 a plurality of heat-dissipating plates installed vertically at intervals on the
heat-conductive base, each of which has a flat body with a plurality of
pillar-like protruding parts and the protruding parts of any two adjacent
heat-dissipating plates do not overlap, forming an airflow space with
10 continuously curved airflow paths in between.
2. The heat-dissipating plate module of claim 1, wherein the protruding parts are
elliptical pillars, round pillars, polygonal pillars, octagonal pillars, hexagonal pillars or
square pillars.
3. The heat-dissipating plate module of claim 1, wherein the distance between any
15 two adjacent protruding parts is the same.
4. The heat-dissipating plate module of claim 1, wherein all of the heat-dissipating
plates are equal in length.
5. The heat-dissipating plate module of claim 1, wherein the centers of the
heat-dissipating plates are on a same line.
- 20 6. The heat-dissipating plate module of claim 1, wherein the outer sides of the
heat-dissipating plates are trimmed.
7. The heat-dissipating plate module of claim 1, wherein the heat-dissipating plates
are fixed on the heat-conductive base by a method selected from gluing and welding.